

## General Plating

**TABLE- 1 (Tin-Plated)**

Plating Code	Top Plating Thickness	Under Plating Thickness	Area	Match Type
1	30 $\mu$ " Tin Min.	Reflow Plated	Overall	Crimp clip terminal
	80 $\mu$ " Tin Min.	30 $\mu$ " Nickel Min.	Overall	Crimp clip terminal
	100 $\mu$ " Tin Min.	30 $\mu$ Nickel Min.	Overall	Solder tail terminal & Board in terminal
	120 $\mu$ " Tin Min.	30 $\mu$ Nickel Min.	Overall	Square or round pin
	120 $\mu$ " Tin	50 $\mu$ Nickel Min.	Overall	SMT type terminal

**TABLE- 2 (Gold -Plated)**

Plating Code	Top Plating Thickness	Under Plating Thickness	Area	Match Type
2	0.8 $\mu$ " Gold Min.	50 $\mu$ " Nickel Min.	Overall	Square or round pin
	1.2 $\mu$ " Gold Min.			Other type
3	15 $\mu$ " Gold Min.	50 $\mu$ " Nickel	Overall	All type
4	30 $\mu$ " Gold Min.	50 $\mu$ " Nickel	Overall	All type
5	50 $\mu$ " Gold Min.	50 $\mu$ " Nickel	Overall	All type
7	3 $\mu$ " Gold Min.	50 $\mu$ " Nickel	Overall	All type
8	80 $\mu$ " Gold Plated over	50 $\mu$ " Nickel	Overall	CP35
9	5 $\mu$ " Gold Plated over	50 $\mu$ " Nickel	Overall	All type
A	Selective 1.2 $\mu$ " Gold Flash	50 $\mu$ " Nickel	Contact Area	All type
B	Selective 15 $\mu$ " Gold	50 $\mu$ " Nickel	Contact Area	All type
C	Selective 30 $\mu$ " Gold	50 $\mu$ " Nickel	Contact Area	All type

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D	Selective 10 $\mu$ ” Gold	50 $\mu$ ” Nickel	Contact Area	All type
E	Selective 50 $\mu$ ” Gold	50 $\mu$ ” Nickel	Contact Area	All type
F	Selective 80 $\mu$ ” Gold	50 $\mu$ ” Nickel	Contact Area	CP35
G	Selective 5 $\mu$ ” Gold	50 $\mu$ ” Nickel	Contact Area	CCF
I	Selective 15 $\mu$ ” Gold	1.2 $\mu$ ” Gold Flash Plated over 50 $\mu$ ” Nickel	Contact Area	All type
J	Selective 30 $\mu$ ” Gold	1.2 $\mu$ ” Gold Flash Plated over 50 $\mu$ ” Nickel	Contact Area	All type
K	Selective 5 $\mu$ ” Gold	80 $\mu$ ” Nickel	Contact Area	All type

### SOLDERABILITY:

TEST ITEM	TEST CONDITION	PROCESS	TEST REQUIREMENT
Solderability	Soldering time: 5 $\pm$ 0.5 Second Soldering pot: 230 $\pm$ 5 $^{\circ}$ C	Sn - Pb Process	Minimum: 95% of immersed area
	Soldering time: 3 $\pm$ 0.5 Second Soldering pot: 245 $\pm$ 5 $^{\circ}$ C	Lead Free Process	